

Emerging metrology requirements for heterogeneous integration and 3D packaging – July 27, 2022



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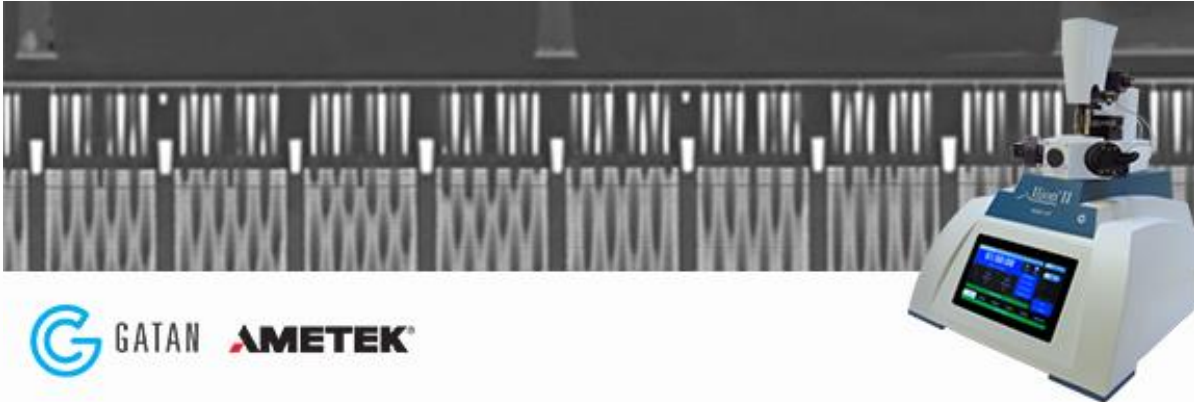
On March 8, Apple held their “Peek Performance” event, introducing the all-new Mac Studio including within it the M1 Ultra processor and its unique (up to now) packaging. **More>>**

Emerging metrology requirements for heterogeneous integration and 3D packaging

The ability to speed up the deployment of heterogeneous integration in mass production requires new and more frequent types of measurements in key manufacturing processes, including wafer and die bonding as well as lithography. **More>>**

Sub-fab “operational excellence” drives factory optimization

In a push to meet the chip supply crunch, fab utilization is at record high of 97%+. In addition, corporate social responsibility (CSR) and sustainability priorities are growing and chip makers are seeking more initiatives to reduce environmental impact. [More>>](#)



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IEEE International Electron Devices Meeting announces program highlights for 2022

The 68th annual IEEE International Electron Devices Meeting, the world's leading forum for the unveiling of breakthroughs in transistors and related micro/nano technologies, will be held December 3-7, 2022 in San Francisco. [More>>](#)

SEMI applauds Senate progress on CHIPS Act of 2022

SEMI applauded progress in the United States Senate on a robust package of federal incentives for the semiconductor supply chain and urged its timely passage in Congress. [More>>](#)



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